



IECQ Certificate of Conformity Capability

IECQ Certificate No.:	IECQ-C BSI 15.0001	Issue No.:	5	Status:	Current
Supersedes:	IECQ-C BSI 15.0001 Issue 4	Issue Date:	2024/01/31	Org Issue:	2003/08/18
CB Reference No.:	026/QCA Issue 13	Expiration:	2027/01/31		

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The organization has developed and implemented procedures and related processes which have been assessed by the IECQ Certification Body issuing this certificate and found to comply with the applicable requirements of the IECQ Approved Component Scheme "Capability Certification" which is in accordance with the Basic Rules IECQ 01 "Rules of Procedure", IECQ 03-1 "IECQ General Requirements for all Schemes" and IECQ 03-3 Annex D "IECQ Approved Components Scheme" of the IEC Quality Assessment System for Electronic Component (IECQ), and in respect of standard(s) or specification(s):

- **BS 123 000 {2001}** System of quality assessment – generic specification -Printed boards

Process Manual Reference: **BS/CM01/IECQ 001 IECQ 03-3 Annex D**

Details of Components/Assemblies/Materials:

Assessment level: C
Incorporating the requirements of ANSI / IPC-A-600 Class 2
Rigid Printed Boards:
Multilayer
Double-sided with plated-through holes
Single & Double-sided with plain holes
Flex-Rigid Printed Boards:
Multilayer with through-connections

-- Attached Schedule: 026_QCA scope Issue 5.pdf --

Issued by the Certification Body (CB): BSI

Kitemark Court, Davy Avenue
Knowlhill, Milton Keynes MK5 8PP
United Kingdom

Authorized person:
Shahm Barhom



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Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 15.0001

CB Certificate No.: 026/QCA

Schedule Number: IECQ-C BSI 15.0001-S

Rev No.: 5

Revision Date: 2024/01/30

Page 1 of 1

Board Types:	Rigid Multilayer			BS 123300-003
	Rigid double-sided with plated through holes			BS 123200-003
	Rigid single & double-sided with plain holes			BS 123100-003
	Flex-Rigid multilayer with through holes			BS 123600-003
Base Materials:	Epoxide Woven Glass			
	Polyimide Film			
Board Size:	495.30 mm x 419.10 mm multilayer			BS 123300-003
	261.87 mm x 322.33 mm multilayer			BS 123600-003
Number of Layers	32 maximum			BS 123300-003
	10 maximum			BS 123600-003
Conductors	0.10 mm (photomech) Tolerance -0.02 mm +0.03 mm			
Plated-through Hole Diameter:	0.20 mm	Minimum	Finished hole size	BS 123300-003
	0.80 mm	Minimum	Finished hole size	BS 123600-003
Aspect Ratio:	16.4 : 1	Maximum		BS 123300-003
	2.27 : 1	Maximum		BS 123600-003
Finishes:	* Hot Air Solder Levelling			
	Immersion Silver			
	2.5µm Gold over Copper Edge Contacts			
	Liquid Photopolymer Solder Resist			
	Legend; UV or Oven Cured			
	Solder resist UV cured			
Additional:	Selective Electroplated Gold (2.5 µm) on Copper			
	Selective Electroless Gold (0.07 µm) on Nickel			

* This finish meets the Solderability requirements

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